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DMG4413LSS-13

Diodes Incorporated MOSFET MOSFET, P-CHANNEL

Any questions, please feel free to contact us. info@kaimte.com





30V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| BV _{DSS} | R _{DS(ON)} max | I _D max T _A = +25°C | |
|-------------------|--|--|--|
| -30V | $7.5 \text{m}\Omega$ @ $V_{GS} = -10V$ | -12A | |
| -307 | 10.2mΩ @ V _{GS} = -4.5V | -10A | |

Description

This MOSFET has been designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Backlighting
- **Power Management Functions**
- DC-DC Converters

Features and Benefits

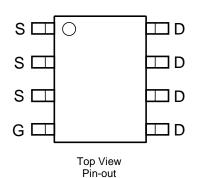
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- Automotive-Compliant Part is Available Under Separate Datasheet (DMG4413LSSQ)

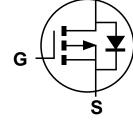
Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram Below
- Terminals: Finish Matte Tin Annealed over Copper Lead Frame. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.074 grams (Approximate)









Equivalent Circuit

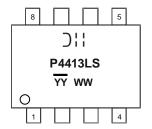
Ordering Information (Note 4)

| Part Number | Case | Packaging |
|---------------|------|------------------|
| DMG4413LSS-13 | SO-8 | 2500/Tape & Reel |

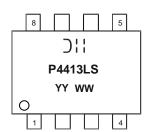
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information







Shanghai A/T Site

) | | = Manufacturer's Marking P4413LS = Product Type Marking Code YYWW = Date Code Marking YY or \overline{YY} = Year (ex: 18 = 2018) WW = Week (01 to 53)

YY = Date Code Marking for SAT (Shanghai Assembly/ Test Site) YY = Date Code Marking for CAT (Chengdu Assembly/ Test Site)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | | |
|---|-----------------|--|------------------|------------|---|
| Drain-Source Voltage | | | V _{DSS} | -30 | V |
| Gate-Source Voltage | | | V _{GSS} | ±20 | V |
| Ocaliana Basis Ocasa (Alata Olivia | Steady State | $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | I _D | -12 -10 | А |
| Continuous Drain Current (Note 6) V _{GS} = -10V | t<10s | $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | I _D | -22 -17 | А |
| Continuous Drain Current (Note 6) \/ 45\/ | Steady State | $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | I _D | -10 -8 | А |
| Continuous Drain Current (Note 6) V _{GS} = -4.5V | t<10s | $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | I _D | -18 -14 | А |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) | | | I _{DM} | -45 | Α |
| Maximum Body Diode Continuous Current | I _S | -4 | Α | | |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit | | |
|---|----------------------|-----------------|------|--------|--|
| Total Power Dissipation (Note 5) | $T_A = +25^{\circ}C$ | D- | 1.7 | W | |
| Total Power Dissipation (Note 5) | $T_A = +70^{\circ}C$ | P_D | 1.1 | | |
| Thermal Pecietanes, Junetien to Ambient (Note 5) | Steady State | D | 74 | °C/W | |
| Thermal Resistance, Junction to Ambient (Note 5) | t<10s | $R_{\theta JA}$ | 22 | - C/VV | |
| Total Power Dissipation (Note 6) | $T_A = +25^{\circ}C$ | р | 2.2 | W | |
| Total Fower Dissipation (Note 6) | $T_A = +70^{\circ}C$ | P_{D} | 1.4 | VV | |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady State | D | 56 | | |
| Thermal Resistance, Junction to Ambient (Note 6) | t<10s | $R_{\theta JA}$ | 17 | °C/W | |
| Thermal Resistance, Junction to Case (Note 6) Steady State | | $R_{	heta JC}$ | 2.5 | | |
| Operating and Storage Temperature Range | $T_{J_1}T_{STG}$ | -55 to +150 | °C | | |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

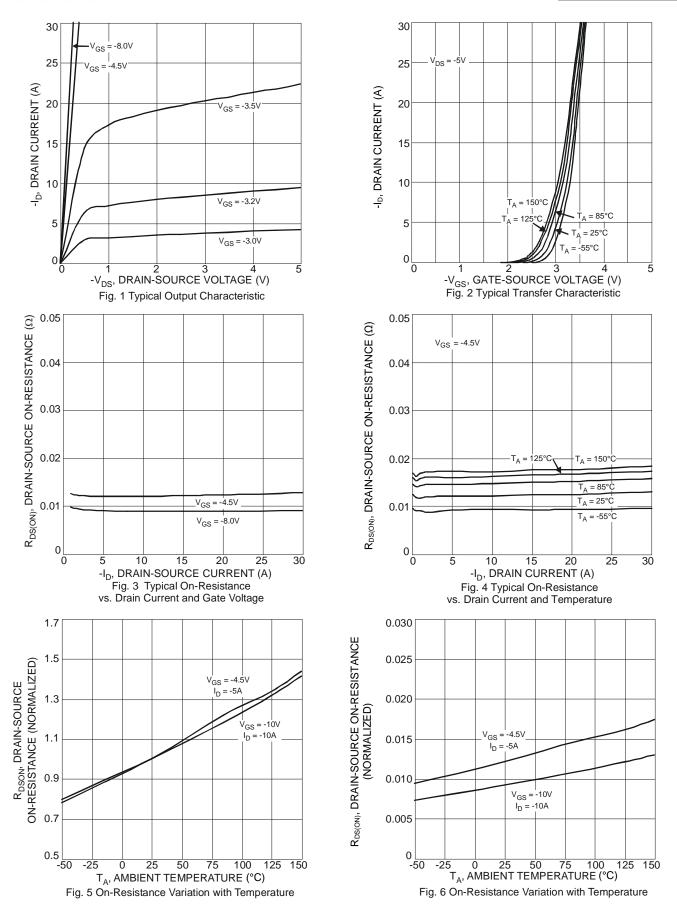
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|------------------------------------|---------------------|------|------------|-------------|--|---|
| OFF CHARACTERISTICS (Note 7) | | | | | • | • |
| Drain-Source Breakdown Voltage | BV _{DSS} | -30 | _ | _ | V | $V_{GS} = 0V, I_D = -250\mu A$ |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | _ | -1 | μΑ | $V_{DS} = -30V, V_{GS} = 0V$ |
| Gate-Source Leakage | I _{GSS} | _ | _ | ±1 | μΑ | $V_{GS} = \pm 20V, V_{DS} = 0V$ |
| ON CHARACTERISTICS (Note 7) | | | | | | • |
| Gate Threshold Voltage | V _{GS(TH)} | -1.1 | -1.6 | -2.1 | V | $V_{DS} = V_{GS}, I_D = -250 \mu A$ |
| Static Drain-Source On-Resistance | R _{DS(ON)} | _ | 6.3 7.9 | 7.5 10.2 | mΩ | $V_{GS} = -10V, I_{D} = -13A$ $V_{GS} = -4.5V, I_{D} = -10A$ |
| Forward Transconductance | g fs | _ | 26 | _ | S | V _{DS} = -15V, I _D = -13A |
| Diode Forward Voltage | V _{SD} | _ | -0.7 | -1.0 | V V _{GS} = 0V, I _S = -2.7A | |
| DYNAMIC CHARACTERISTICS (Note 8) | | | | | | • |
| Input Capacitance | C _{iss} | _ | 4965 | _ | pF | \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\ |
| Output Capacitance | Coss | _ | 1487 | _ | pF | $V_{DS} = -15V, V_{GS} = 0V$ - $f = 1.0MHz$ |
| Reverse Transfer Capacitance | C _{rss} | _ | 711 | _ | pF | 1 = 1.000112 |
| Gate Resistance | R _G | _ | 7.3 | _ | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$ f = 1.0MHz |
| SWITCHING CHARACTERISTICS (Note 8) | | | | | | • |
| Total Gate Charge | Q_G | _ | 46 | _ | | $V_{DS} = -15V, V_{GS} = -5V$ $I_{D} = -13A$ |
| Gate-Source Charge | Q _{GS} | _ | 17 | _ | nC | |
| Gate-Drain Charge | Q_{GD} | _ | 16 | _ | | |
| Turn-On Delay Time | t _{D(ON)} | _ | 15 | _ | | |
| Rise Time | t _R | _ | 9 | _ | | $V_{DS} = -15V$, $V_{GS} = -10V$, |
| Turn-Off Delay Time | t _{D(OFF)} | _ | 160 | _ | ns | $I_D = -1A, R_G = 6.0\Omega$ |
| Fall Time | t _F | _ | 66 | _ | | |

Notes:

- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.

- 8. Guaranteed by design. Not subject to product testing.









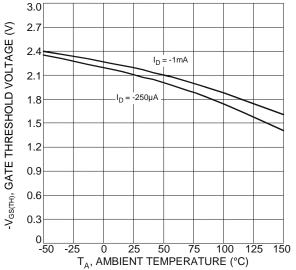
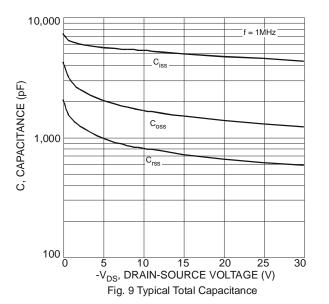
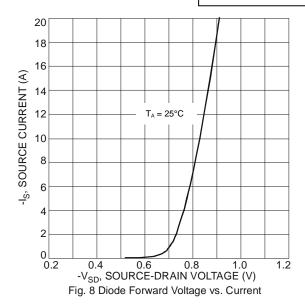
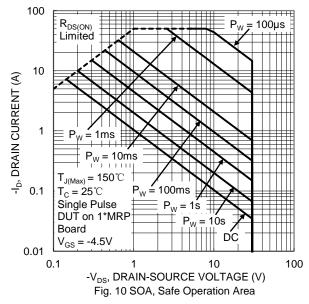


Fig. 7 Gate Threshold Variation vs. Ambient Temperature





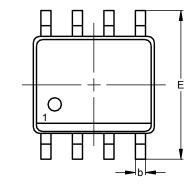


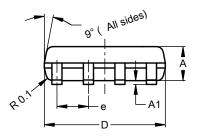


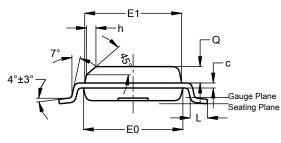
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8





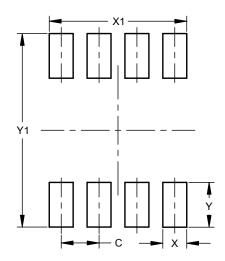


| SO-8 | | | | | |
|----------------------|------|------|------|--|--|
| Dim | Min | Max | Тур | | |
| Α | 1.40 | 1.50 | 1.45 | | |
| A1 | 0.10 | 0.20 | 0.15 | | |
| b | 0.30 | 0.50 | 0.40 | | |
| С | 0.15 | 0.25 | 0.20 | | |
| D | 4.85 | 4.95 | 4.90 | | |
| Е | 5.90 | 6.10 | 6.00 | | |
| E1 | 3.80 | 3.90 | 3.85 | | |
| E0 | 3.85 | 3.95 | 3.90 | | |
| е | | | 1.27 | | |
| h | - | | 0.35 | | |
| L | 0.62 | 0.82 | 0.72 | | |
| Q | 0.60 | 0.70 | 0.65 | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8



| Dimensions | Value (in mm) | | |
|------------|---------------|--|--|
| С | 1.27 | | |
| Х | 0.802 | | |
| X1 | 4.612 | | |
| Υ | 1.505 | | |
| Y1 | 6.50 | | |



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